

IN THE CLAIMS

1. (Currently Amended) An energization processing apparatus for performing, in a reduced-pressure atmosphere, an energization process on electric conductors which are placed on a substrate, comprising:

a vessel which has an exhaust hole and which covers the electric conductors and one region on a surface of the substrate where the electric conductors are placed, to create an airtight atmosphere between the substrate and the vessel, wherein the vessel does not cover a further region on the surface of the substrate;

a first temperature adjusting mechanism for generating a heat quantity to adjust a temperature of ~~adjusting a temperature of~~ the one region ~~on the surface of the substrate covered with the vessel;~~ and

a second temperature adjusting mechanism for generating a heat quantity to adjust a temperature of ~~adjusting a temperature of another~~ the further region on ~~the surface of the substrate not covered with the vessel,~~

wherein the heat quantity generated by the first temperature adjusting mechanism is different from the heat quantity generated by the second temperature adjusting mechanism.

2. (Canceled)

3. (Currently Amended) An energization processing method for performing, in a reduced-pressure atmosphere, an energization process on electric conductors which are placed on a substrate, comprising the steps of:

covering the electric conductors and one region on a surface of the substrate where the electric conductors are placed with a vessel which has an exhaust hole, to create an airtight atmosphere between the substrate and the vessel, wherein the vessel does not cover a further region on the surface of the substrate;

reducing a pressure of the airtight atmosphere; and

heating the one region with a smaller heat quantity while heating the
~~another further region on the surface of the substrate not covered with the vessel with a~~
~~larger heat quantity larger than a heat quantity for heating the one region on the surface of~~
~~the substrate covered with the vessel; so as to suppress a temperature difference between~~
~~the one region covered with the vessel and the further region not covered with the vessel.~~

4. (Canceled)

5. (Currently Amended) The energization processing apparatus according to claim 1, wherein

the first temperature adjusting mechanism has a first thermal conducting member touching a surface of the substrate just opposite to the one region ~~covered with the vessel~~, while the second temperature adjusting mechanism has a second

thermal conducting member touching a surface of the substrate just opposite to the ~~another~~
further ~~region not covered with the vessel.~~

6. (Currently Amended) The energization processing apparatus
according to claim 1, wherein
the second temperature adjusting mechanism is capable of thermal
generation larger than that of the first temperature adjusting mechanism, to suppress a
temperature difference between the one region ~~covered with the vessel~~ and the ~~another~~
further ~~region not covered with the vessel.~~